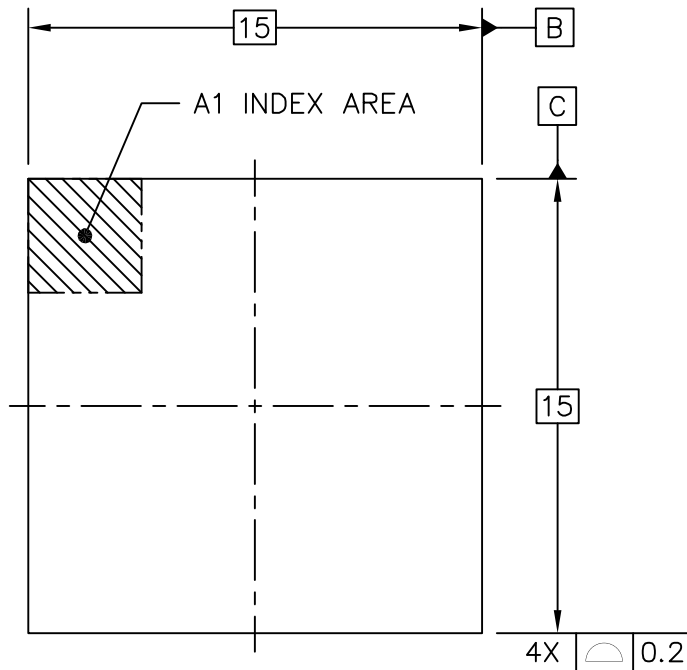
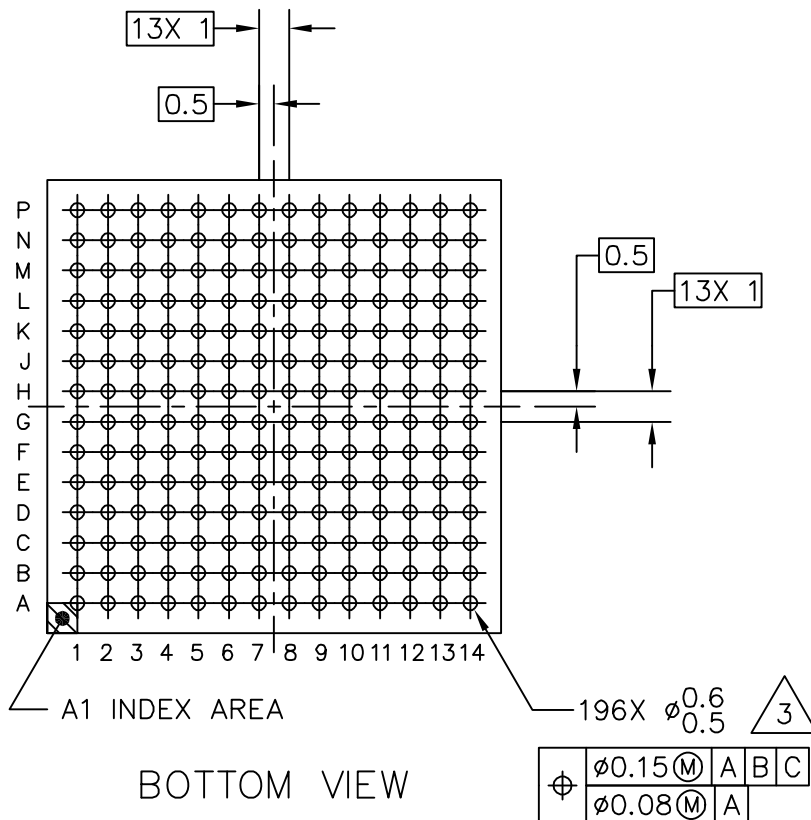
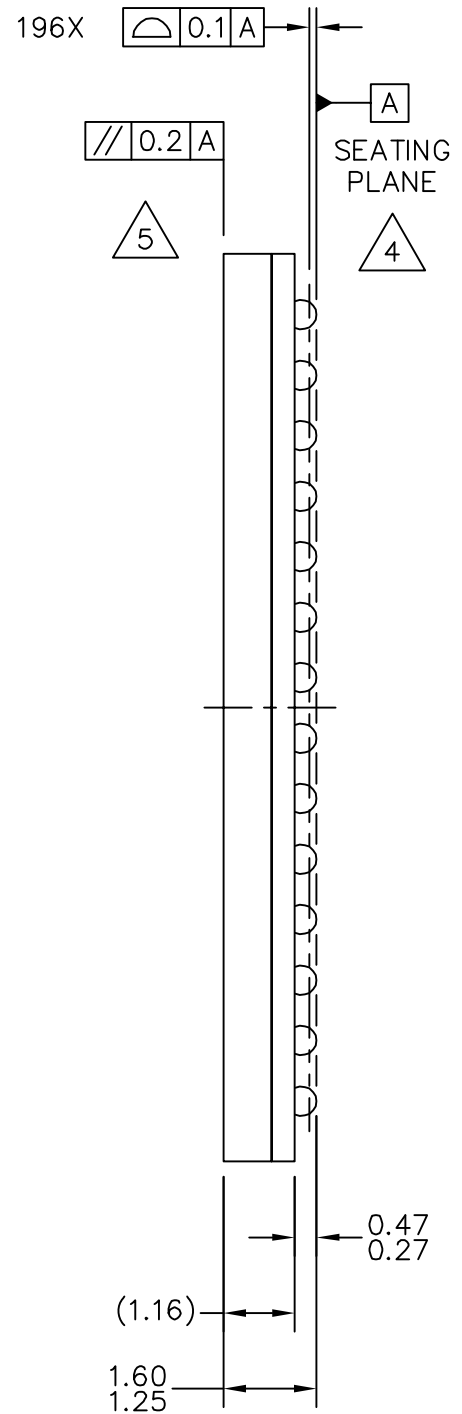




TOP VIEW



BOTTOM VIEW



SIDE VIEW

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: PBGA, LOW PROFILE,
196 I/O, 15 X 15 PKG,
1 MM PITCH (MAP)

DOCUMENT NO: 98ARH98217A

REV: D

CASE NUMBER: 1128C-03

26 NOV 2010

STANDARD: NON-JEDEC

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. PACKAGE CODES:
5220 - FINE PITCH WIRE BONDING
5354 - STANDARD PITCH WIRE BONDING
004N - MRAM Ni-Fe FOIL OPTION WITH FINE PITCH WIRE BONDING

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TITLE: PBGA, LOW PROFILE, 196 I/O, 15 X 15 PKG, 1 MM PITCH (MAP)		DOCUMENT NO: 98ARH98217A		REV: D	
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